

Remarks:

Applicants thank Examiner Perez-Daple again for his careful examination of this application and clear explanation of the rejections. In response, applicants amend this application, canceling claims 1 – 27 and insert new claims 28 and 29.

New claims stand patentable over the references in the Office action for the reason set forth below:

Claim 27 describes a system of multiple bonders that are communicatively connected. Each bonder has an optical unit and a memory unit for storing files of data and images, is able to manipulate data stored in the memory and is capable of controlling the bonding operation based on the information generated in the bonder.

The system also comprises a semiconductor chip with multiple bondpads that are grouped into segments. Each segment has its own reference related to the bondpads in that segment. The bondpad location and the segment information are included in a device file that is downloadable from a bonder to another bonder.

Each bonder is capable to use its optical unit to capture visual images of the chip loaded on it and to store the imagery information in the memory. The bonder then is capable to generate a corrective data set based on the device file and the visual information to control the bonding operation.

The Kono reference does not disclose communicative multiple bonders and neither the Kono reference nor the Koduri '963 patent disclose segmenting the bondpads in its compensating function. The advantages of segmenting the bondpads are explained clearly in the specification. For example, in the original specification, it is explained that errors in x-y tables and motors are not easily compensated if the chip size is large.¹ Segmenting the bondpads overcomes such difficulties.

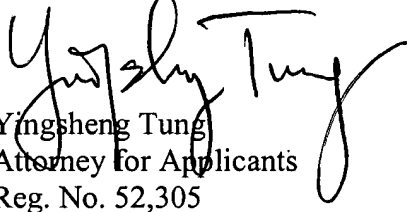
The Seki reference is related to a CAD system and it lacks many elements in claim 27.

Because the new claim 27 clearly distinguishes from the cited references, applicants respectfully submit that claim 27 stands patentable.

For the same reason, new claim 28 stands patentable. Claim 28 describes a method of bonding a semiconductor chip with a multi-bonder system and the steps in the method involve many of the same elements in claim 27 that are not disclosed in the cited references.

Applicants respectfully submit that as amended, this application is in allowable form; new claims 27 and 28 distinguish from the cited references and are patentable. Applicants respectfully request that the application be further examined and the claims pass to allowance.

Respectfully submitted,



Yingsheng Tung
Attorney for Applicants
Reg. No. 52,305

Texas Instruments Incorporated
P. O. Box 655474, MS 3999
Dallas, Texas 75265
(972) 917-5355